


MATERIAL DECLARATION SHEET



Material Number	CRM2512			
Product Line	High power chip resistors			
Compliance Date	7-27-2007			
RoHS Compliant	Yes (Lead Exemption)	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic	Substrate	34.7435	Aluminum oxide	1344-28-1	96	83.687	87.174
				Silicon dioxide	7631-86-9	4	3.487	
				Magnesium oxide	1309-48-4			
2	Top conductor	Silver	0.6157	Silver	7440-22-4	100	1.545	1.545
3	Bottom conductor	Silver	0.3152	Silver	7440-22-4	100	0.791	0.791
4	Resistor	Ruthenium Oxide	0.3821	Silver	7440-22-4	40	0.383	0.959
				Ruthenium dioxide	12036-10-1	20	0.192	
				Palladium	7440-05-3	15	0.144	
				Lead glass	7439-92-1	25	0.240	

MATERIAL DECLARATION



5	First encapsulating	Resin	0.3685	Bismuth trioxide	1304-76-3	50	0.463	0.925
				Resin	25036-25-3	30	0.278	
				Aluminum oxide	1344-28-1	10	0.092	
				Boron	7440-42-8	10	0.092	
6	Overcoat	Epoxy	0.8454	Epoxy	25036-25-3	100	2.121	2.121
7	Side conductor	Silver	0.8142	Silver	7440-22-4	85	1.737	2.043
				Epoxy	9003-36-5	15	0.306	
8	Plating (Middle)	Nickel	0.6872	Nickel	7440-02-0	100	1.724	1.724
9	Plating (Outer)	Tin	1.0308	Tin	7440-31-5	100	2.586	2.586
10	Marking	Epoxy	0.0525	Epoxy	25068-38-6	70	0.092	0.132
				Titanium dioxide	1317-80-2	30	0.040	
Total weight			39.8551					

This Document was updated on: 10/29/2010

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. RoHS exemption 7c-I - Lead in glass of ... electronic components.